

AMENDMENT AND RESPONSE TO OFFICE ACTION

In response to the Office Action mailed on January 18, 2001 regarding the above-referenced application, the Applicant respectfully requests consideration of the following amendments and remarks.

IN THE FIGURES

Applicant has amended Figures 1 and 2 in red ink. Applicant respectfully requests the Examiner's approval of the amendment to these figures.

IN THE CLAIMS

Please cancel claims 20-21 without prejudice or disclaimer of the subject matter contained therein and amend the claims as follows.

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14. (Three Times Amended) An apparatus comprising:
- 4/2*
- a first substrate with a semiconductor film formed thereon;
- wherein a bond between said semiconductor film and said first substrate is weakened by a hydrogen ion implanted damaged surface, said semiconductor film is demarcated from a rest of said first substrate by the hydrogen ion implanted damaged surface.
- E1*
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